What is claimed is:

1. A performance-adjusting device for inertia sensor includes:

a suspension structure, one side of which is connected firmly to a supporting piece, such that another side of the suspension structure is shown as a suspending state; and

a micro-electroplating structure, which is formed at another side of the suspension structure by micro-electroplating process and is shown as suspending state with a specific altitude.

2. The performance-adjusting device for inertia sensor according to claim 1, wherein the suspension structure is further comprised of:

an arm, one side of which is arranged firmly at a supporting piece, such that another side of the arm is shown as a suspending state; and

a platform, which is arranged at one side, of the arm, shown as suspending state, and the platform is configured by horizontally extending a specific length to two sides by taking the arm as center, and a micro-electroplating structure is respectively arranged at two top sides of the platform.

3. The performance-adjusting device for inertia sensor according to claim 2, wherein the suspension structure is arranged reinforcing structure, which is comprised of:

inside reinforcing structure, which is arranged at two top sides of the arm and is extended along the inside of the platform and is connected to the micro-electroplating structure; and

outside reinforcing structure, which is arranged at the outside of the platform and is not connected to the micro-electroplating structure.

4. The performance-adjusting device for inertia sensor according to claim 1, wherein the suspension structure is a vibratory structure arranged on the inertia sensor.

5. The performance-adjusting device for inertia sensor according to claim 1, wherein the suspension structure is processed by surface micromachining, or by bulk micromachining technique incorporating with

thin film technique.

6. The performance-adjusting device for inertia sensor according to claim 1, wherein the suspension structure includes supporting structure, signal-connecting path, and signal-isolation layer.

7. The performance-adjusting device for inertia sensor according to claim 1, wherein the micro-electroplating process includes following steps:

(a) Preparing a suspension-based structure;

(b) Electroplating a plating seed layer upon the suspension-based structure;

(c) Setting up a thick film photoresist of isolation upon the plating seed layer;

(d) Forming metallic plating layer having a specific thickness between each thick film photoresist;

(e) Removing the thick film photoresist;

(f) Removing the plating seed layer; and

(g) Removing the sacrificial layer, and forming a suspension structure constructed by both suspension structure layer and the metallic plating layer.